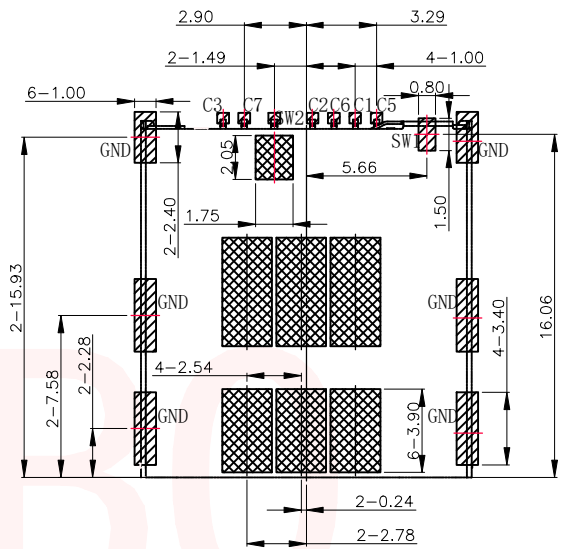
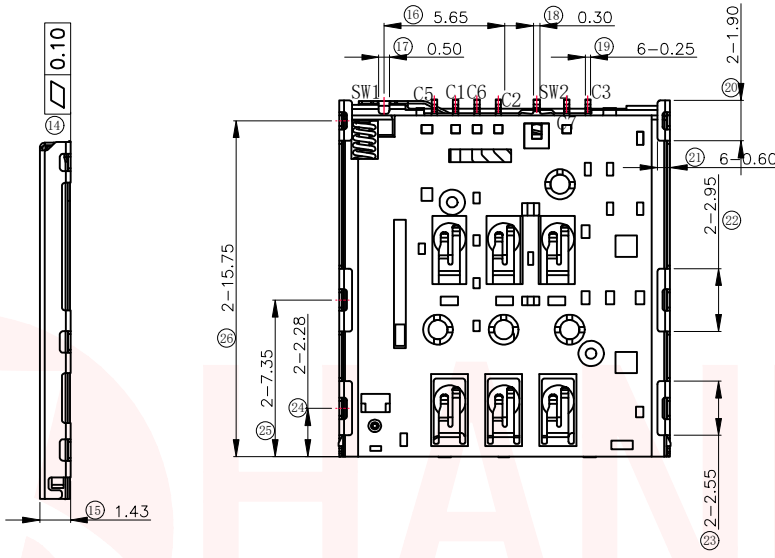
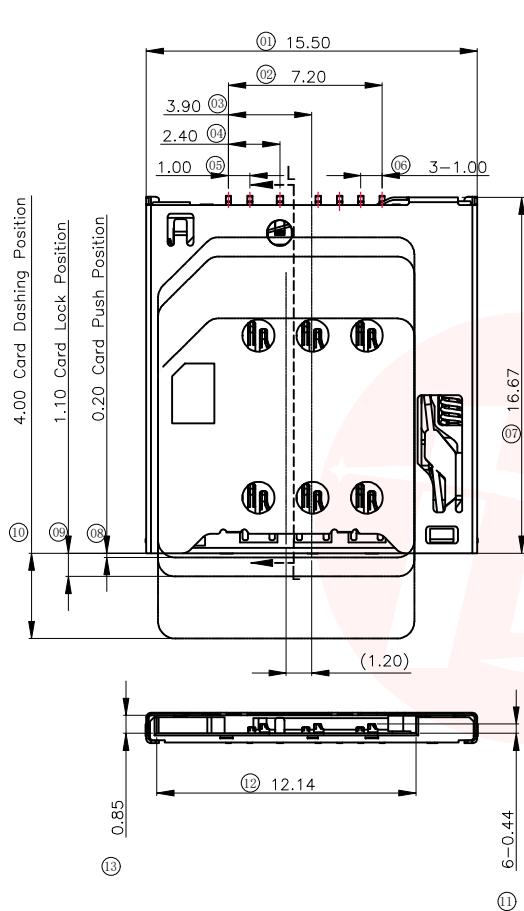




REV.	ECN NO OR DESCRIPTION	REVISED	DATE



RECOMMENDED PCB LAYOUT

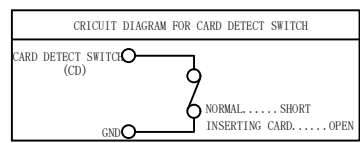
TOLERANCE: ±0.05

- SMT SOLDER AREA
- COPPER RESTRICTED AREA
- 1. TOUCH AREA OF CONTACT
- TIPS NO ELECTRICAL FUNCTION
- 2. NO FIRST PCB_LAYOUT
- CIRCUITS IN THE AREA

Notes:

1. Material:
Housing: High Temperature Thermoplastic
Terminal: Copper Alloy
Shell: Stainless Steel
2. Plating:
Terminal: 50u" Ni Underplated Overall
G/F Plated On Contact Area
Tin Plated On Solder Area
Shell: 50u" Ni Underplated Overall
G/F Plated On Contact Area And older Area
3. Technical Speciality:
Rated Voltage: 30V
Current Rating: 0.5A
Insulation Resistance: 1000MΩ Min.
Contact Resistance: 100mΩ Max.
Withstanding Voltage: 500V DC For 1 Minutes.
Operating Temperature: -40°C~+75°C Humidity 80% R.H Max.

PIN/NO	ASSIGNMENT
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O
SW1	Detect Lever/GND
SW2	Detect Switch



UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:
X : ±0.30	X : ±2°
X.X : ±0.20	X.X : ±1°
X.XX : ±0.10	

东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO., LTD

TITLE	1.42H PUSH-PUSH MICRO SIM CARD			
DWN	xiong	PART NO. SMO-1570S		
CHKD	lee	SCALE: 1:1	UNIT: mm	
APVD	wang	SIZE: A4	SHEET: 10F 1	REV: A4
CUSTOMER COPY				